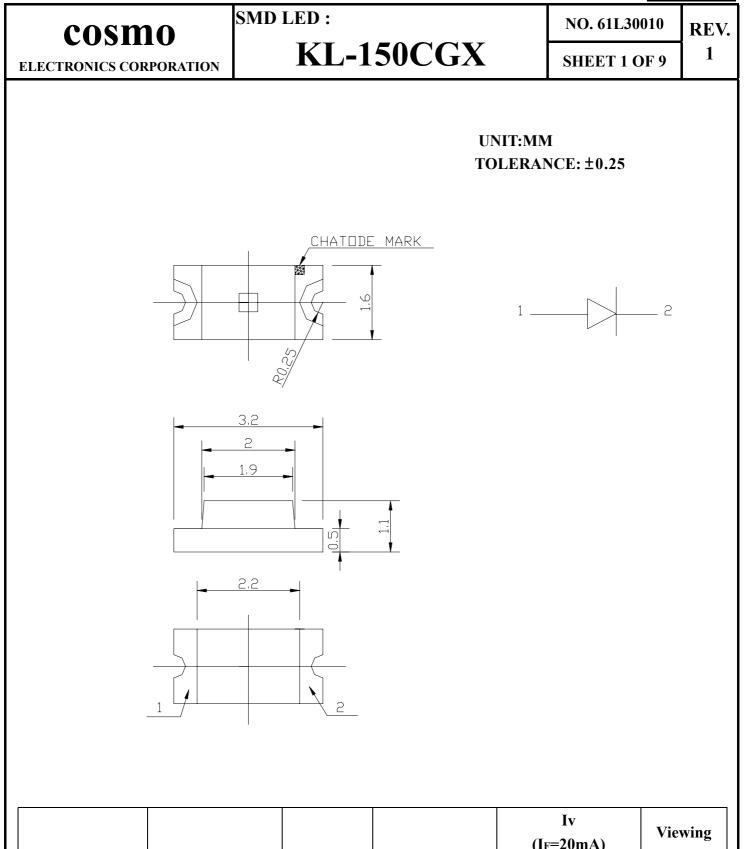
DATE: 08/11/2004



Part No.	Emitting Color	Material	Lens Type	(IF=2 MIN (mcd)	0mA) TYP (mcd)	Viewing Angle 2 <i>θ</i> 1/2
KL-150CGX	Super brightness green	InGaN	Water Clear	165	230	120°

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1

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KL-150CGX

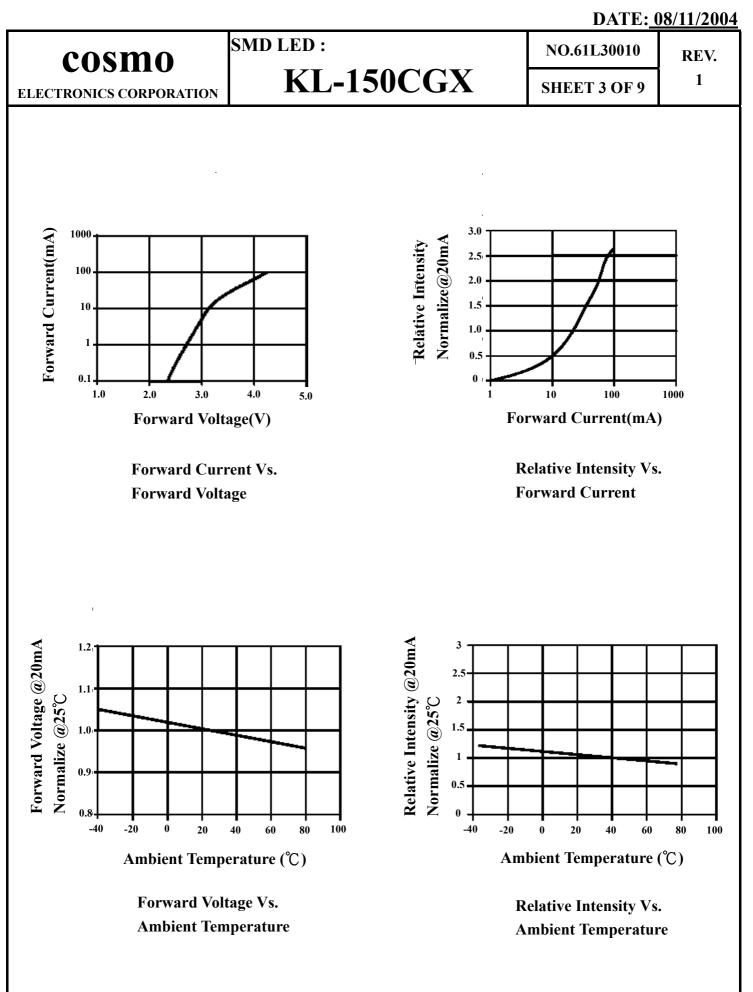
NO. 61L30010 REV. SHEET 2 OF 9

ELECTRONICS CORPORATION

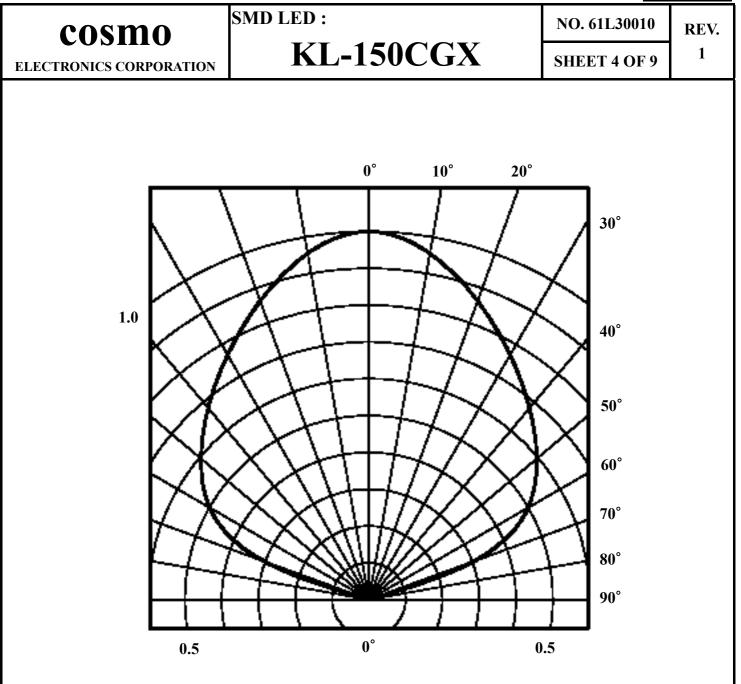
Absolute maximum ratings (TA=25°C)		T2G Green (InGaN)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	Ifp	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	105	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тѕт	-40~+85	°C
LED DISPLAYS:			
Operating temperature	ТА	-40~+85	°C
Storage temperature	Тятс	-40~+85	°C

Operating characteristics (TA=25°C)		T2G Green (InGaN)	Unit
Forward voltage(typ.) IF=20mA	VF	3.5	V
Forward voltage(max.) IF=20mA	VF	4.0	V
Reverse current(max.) V _R =5V	Ir	10	uA
Wavelength at dominant emission(typ.)	λ d	525	nm
IF=20mA Wavelength at peak	λ Ρ	523	nm
emission(typ.) IF=20mA Spectral line half-width	Δλ	36	nm
IF=20mA Capacitance	C C	20	pF
VF=0V,f=1MHz	U U		

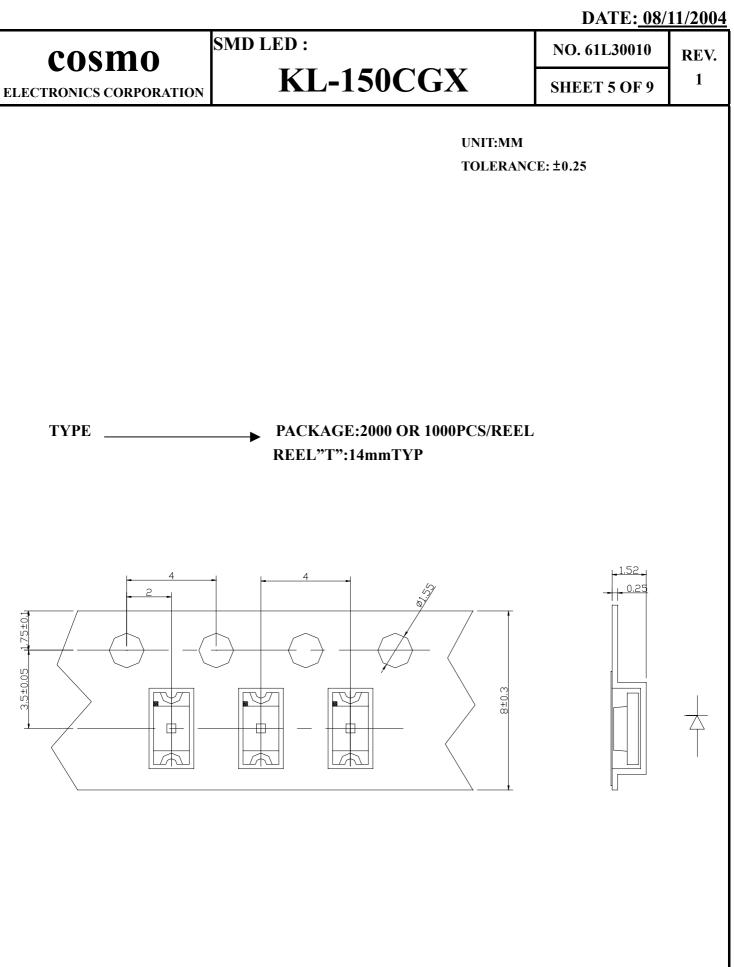
SMD LED :

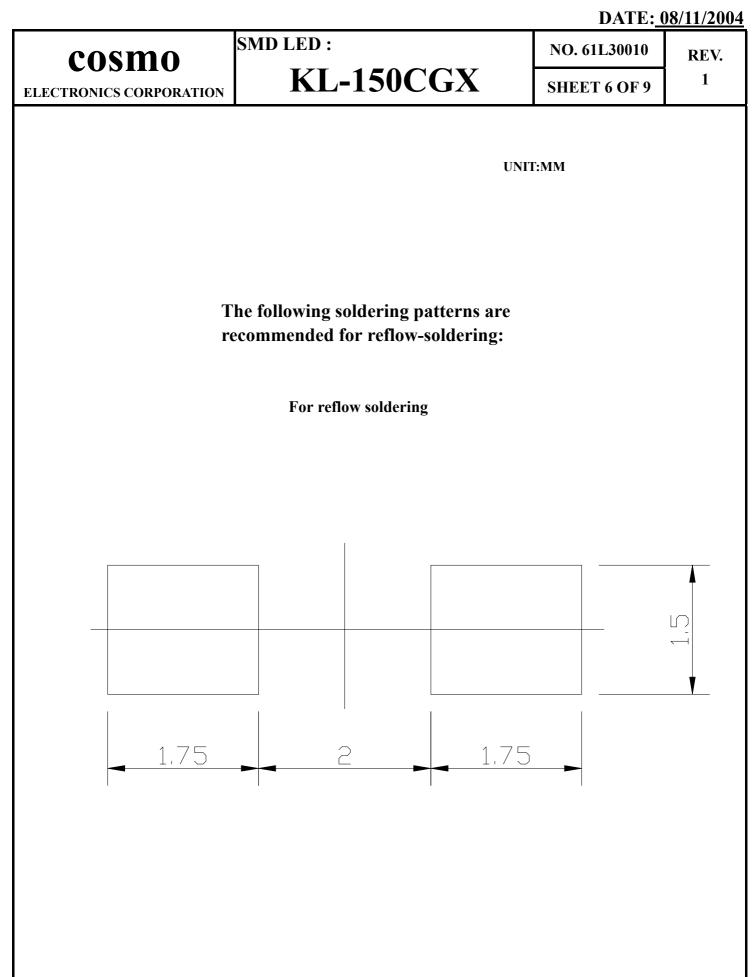


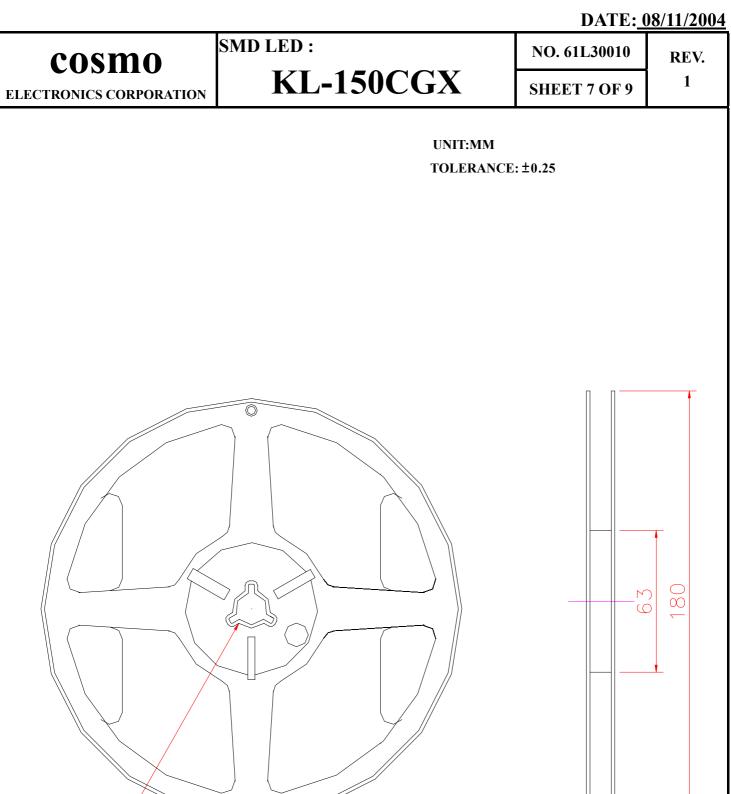
DATE: 08/11/2004



View Angle 2 ∂1/2=120°







12.5

15



DATE: 08/11/2004 **SMD LED :** NO. 61L30010 cosmo REV. **KL-150CGX** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING SMT REFLOW SOLDERING INSTRUCTIONS** 10 sec MAX Temp (°C) TEMPERATURE 230 4° C/sec max 140~160°C - 4° C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** i(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** MAXLMUM DISTANCE FORM **TEMPERATURE OF** MAXLMUM DISTANCE FROM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME TO CASE ≦**260**°C 3S >2mm **≦260**°C 3S >2mm LEDS ≦**260**°C 5S >4mm ≦**260**°C 5S >4mm DISPLAYS ≤**260**°C 3S >2mm ≤**260**°C 3S >2mm

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SMD LED :

KL-150CGX

SMD HANDLING AND APPLICATION PRECAUTIONS

STORAGE

(1.1) It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature: $5^{\circ}C \sim 30^{\circ}C$ (41°F ~ 86°F)

(1.2)Shelf life in sealed bag: 12 month at $<5^{\circ}$ C $\sim30^{\circ}$ C and $<30^{\circ}$ RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at $\leq 20\%$ RH in zip -locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a) $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b) $100\pm3^{\circ}C$ x (45min~1hr), loose packing type, or
- (c) $130\pm3^{\circ}C$ x (15~30min), loose packing type

ELECTRIC STATIC DISCHARGE(ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.

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